



2019 Asia-Pacific Microwave Conference (APMC) and Technical Exhibition in Singapore

Active Devices and Circuits

Low-noise devices and circuits, high-power devices and circuits, wide band-gap devices, microwave tubes, control circuits (mixer, oscillator, switch, etc.), MMICs, RFICs, millimeter and THz wave devices and circuits, graphene devices, and other relevant topics.

Passive Components

Multiband, broadband, tunable, and reconfigurable filters, resonators, directional couplers and hybrids, waveguides and transmission lines, ferrite and SAW devices, RF MEMS, LTCC devices, packaging, metamaterials and EBG structures, plasmonic and optical components, nanomaterials, and other relevant topics.

Systems

5G systems, high-speed and broadband millimeter and THz wave systems, MIMO systems, microwave photonics, radar and sensor systems, IoT/M2M/RFID systems, wearable devices and systems, security and health monitoring systems, wireless power transfer systems, energy harvesting devices and systems, microwave medical and biomedical applications systems, whitespace systems, software defined/cognitive/smart radio systems, satellite systems, near/far field measurement, EMC/EMI, SI/PI, microwave heating and chemistry, and other relevant topics.

Antennas and Propagation

EM field theory, EM wave propagation, wave scattering and inverse scattering, DOA estimation, localization, antenna theory and design, millimeter-wave/THz and optical antennas, small antennas, broadband and multi-band antennas, MIMO antennas, active adaptive and smart antennas, reconfigurable antennas, body channel modelling, and other relevant topics.

Emerging Areas

Nano-electromagnetics, artificial intelligence, machine learning and deep learning for microwave and wireless applications, electromagnetic-acoustics, and other relevant topics.

All accepted and presented papers will be included and published in IEEE Xplore.

Technical Exhibition

The Technical Exhibition on RF/microwave/EMC components, devices, materials, measurements, instrumentation and software will be the major accompanying event of the Asia-Pacific Microwave Week.

This exhibition will provide a diverse array of opportunities to showcase and network with tech companies in an exciting venue hosting major manufacturers and distributors of RF/microwave-related equipment, software, and tools.

Important Dates

Table with 2 columns: Event and Date. Includes: Proposals for special sessions & workshops and tutorials CLOSED (June 10, 2019), Preliminary paper submission (July 15, 2019), Notification of acceptance (August 30, 2019), Final paper submission (September 20, 2019).

Call for Papers

Organizing Committee

General Chair Arokiaswami Alphones, Nanyang Technological University, Singapore

General Co-Chairs Yongxin Guo, National University of Singapore, Singapore

Michael Ong, A*STAR I2R, Singapore

Honorary Chairs Tatsuo Itoh, University of California Los Angeles, USA

Dim-Lee Kwong, A*STAR I2R & IME, Singapore

Roberto Sorrentino, University of Perugia, Italy

International Advisory Committee Co-chairs Wei Hong, Southeast University, China

Naoki Shinohara, Kyoto University, Japan

Kiat Seng Yeo, Singapore University of Technology and Design, Singapore

Technical Program Committee Co-chairs Xudong Chen, National University of Singapore, Singapore

Yuanjin Zheng, Nanyang Technological University, Singapore

Richard Xian-Ke Gao, A*STAR IHP, Singapore

Award Committee Co-Chairs Yueping Zhang, Nanyang Technological University, Singapore

Ke Wu, University of Montreal, Canada

Workshop/Tutorial Co-Chairs Eng Leong Tan, Nanyang Technological University, Singapore

Cheng-Wei Qiu, National University of Singapore, Singapore

Finance Chair Muhammad Faeyz Karim, Nanyang Technological University, Singapore

Publication Chair Bin Luo, A*STAR I2R, Singapore

Publicity Chair Kush Agarwal, WaveScan Technologies Pte. Ltd., Singapore

Exhibition & Sponsorship Chair Terence Shie Ping See, A*STAR I2R, Singapore

Local Arrangement Chair Wang Ling Goh, Nanyang Technological University, Singapore

